

MIL-M-38510/60A
5 AUGUST 1985
SUPERSIDING
MIL-M-38510/60 (USAF)
29 March 1974

MILITARY SPECIFICATION

MICROCIRCUITS, DIGITAL, ECL, MULTIPLE NOR GATES, MONOLITHIC SILICON

This specification is approved for use by all Departments and Agencies of the Department of Defense.

1. SCOPE

1.1 Scope. This specification covers the detail requirements for monolithic, silicon, ECL, logic gating microcircuits. Two product assurance classes and a choice of case outlines and lead finishes are provided and are reflected in the complete part number.

1.2 Part number. The complete part number shall be in accordance with MIL-M-38510.

1.2.1 Device type. The device type shall be as follows:

<u>Device type</u>	<u>Circuit</u>
01	Quad OR/NOR gate with strobe
02	Triple NOR gate, single OR/NOR gate
03	Triple 2-3-2 OR/NOR gate
04	Triple 3-4-3 NOR gate
05	Triple exclusive OR/NOR gate
06	Dual 4-5 OR/NOR gate

1.2.2 Device class. The device class shall be the product assurance level as defined in MIL-M-38510.

1.2.3 Case outline. The case outline shall be designated as follows:

<u>Outline letter</u>	<u>Case outline (see MIL-M-38510, appendix C)</u>
E	D-2 (16 pin, 1/4" x 7/8"), dual-in-line package
F	F-5 (16 pin, 1/4" x 3/8"), flat-package
2	C-2 (20-terminal, .350" x .350"), square chip carrier package

1.3 Absolute maximum ratings.

Supply voltage range - - - - -	0 V dc to -7.0 V dc
Input voltage range- - - - -	0 V dc to -5.2 V dc
Storage temperature range- - - - -	-65°C to +150°C
Maximum power dissipation (P_d) per gate- - - -	55 mW 1/
Lead temperature (soldering 10 seconds)- - - -	+260°C
Junction temperature (T_j)- - - - -	165°C 2/
Maximum output current - - - - -	-50 mA
Thermal resistance junction to case (θ_{JC})- - -	See MIL-M-38510, appendix C
Cases E and F- - - - -	60°C/W 3/
Case 2 - - - - -	

- 1/ Must withstand the added P_d due to short circuit test (e.g. I_{OS}).
2/ Maximum junction temperature shall not be exceeded except for allowable short duration burn-in screening conditions per method 5004 of MIL-STD-883.
3/ When a thermal resistance value is included in MIL-M-38510 appendix C, it shall supersede the value stated herein.

[Beneficial comments (recommendations, additions, deletions) and any pertinent date which may be of use in improving this document should be addressed to: Rome Air Development Center (RBRD), Griffiss AFB, NY 13441, by using the self-addressed Standardization Document Improvement Proposal (DD Form 1426) appearing at the end of this document or by letter.]

1.4 Recommended operating conditions.

Supply voltage (V_{EE})	- - - - -	-5.46 V minimum to -4.94 V maximum
Minimum high level input voltage	- - - - -	-1.105 V at $T_C = 25^\circ C$
(@ 500 linear feet per minute (ft/min))		-1.000 V at $T_C = 125^\circ C$
Maximum low level input voltage	- - - - -	-1.255 V at $T_C = -55^\circ C$
(@ 500 linear ft/min)		-1.475 V at $T_C = 25^\circ C$
Normalized fanout (each output)	- - - - -	10 ^{4/}
Operating temperature range	- - - - -	-55 $^\circ C$ to +125 $^\circ C$
(@ 500 linear ft/min)		-1.400 V at $T_C = 125^\circ C$
		-1.510 V at $T_C = -55^\circ C$

2. APPLICABLE DOCUMENTS

2.1 Government specifications and standards. Unless otherwise specified, the following specifications and standards, of the issue listed in that issue of the Department of Defense Index of Specifications and Standards specified in the solicitation, form a part of this specification to the extent specified herein.

SPECIFICATION

MILITARY

MIL-M-38510 - Microcircuits, General Specification for.

STANDARDS

MILITARY

MIL-STD-883 - Test Methods and Procedures for Microelectronics.

(Copies of specifications, standards, handbooks, drawings, and publications required by the manufacturers in connection with specific acquisition functions should be obtained from the contracting activity or as directed by the contracting officer.)

2.2 Order of precedence. In the event of a conflict between the text of this specification and the references cited herein, the text of this specification shall take precedence.

3. REQUIREMENTS

3.1 Detail specification. The individual item requirements shall be in accordance with MIL-M-38510, and as specified herein.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-M-38510 and herein.

3.2.1 Logic diagram and terminal connections. The logic diagram and terminal connections shall be as specified on figure 1.

3.2.2 Truth tables and logic equations. The truth tables and logic equations shall be specified on figure 2.

3.2.3 Schematic circuits. Schematic circuits shall be submitted to the preparing activity prior to inclusion of a manufacturer's device in the specification and shall be submitted to the qualifying activity and agent activity (DESC-ECS) as a prerequisite for qualification. All qualified manufacturers schematics shall be maintained by the agent activity and will be available upon request.

3.2.4 Case outlines. Case outlines shall be in accordance with 1.2.3.

3.3 Lead material and finish. Lead material and finish shall be in accordance with MIL-M-38510 (see 6.4).

4/ Device will fanout in both high and low levels to the specified number of data inputs on the same device type as that being tested.

3.4 Electrical performance characteristics. The electrical performance characteristics are as specified in table I and apply over the full recommended case operating temperature range, unless otherwise specified.

TABLE I. Electrical performance characteristics.
(Limits are valid provided circuit is in a test socket and transverse air flow of 500 linear ft/min is maintained.)

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq 125^{\circ}\text{C}$			Device type	Limits		Units	
		T_C	V_{IH1}	V_{IL1}		Min	Max		
High-level output voltage	V_{OH}	$V_{EE} = -5.2\text{ V}$ $V_{CC} = 0\text{ V}$ Load = 100Ω to -2 V	25°C 125°C -55°C	-0.720 V -0.580 V -0.830 V	-1.850 V -1.820 V -1.920 V	A11	-0.930 -0.825 -1.080	-0.720 -0.580 -0.830	Volts
Low-level output voltage	V_{OL}	$V_{EE} = -5.2\text{ V}$ $V_{CC} = 0\text{ V}$ Load = 100Ω to -2 V	25°C 125°C -55°C	-0.720 V -0.580 V -0.830 V	-1.850 V -1.820 V -1.920 V	A11	-1.350 -1.820 -1.920	-1.620 -1.545 -1.655	Volts
High-level threshold output voltage	V_{OTH}	$V_{EE} = -5.2\text{ V}$ $V_{CC} = 0\text{ V}$ Load = 100Ω to -2 V	25°C 125°C -55°C	-1.105 V -1.000 V -1.255 V	-1.475 V -1.400 V -1.510 V	A11	-0.950 -0.845 -1.100	---	Volts
Low-level threshold output voltage	V_{OTL}	$V_{EE} = -5.2\text{ V}$ $V_{CC} = 0\text{ V}$ Load = 100Ω to -2 V	25°C 125°C -55°C	-1.105 V -1.000 V -1.255 V	-1.475 V -1.400 V -1.510 V	A11	---	-1.600 -1.525 -1.635	Volts
Power supply drain current	I_{EE}	$V_{EE} = -5.2\text{ V}$ $V_{CC} = 0\text{ V}$			01, 02, 03, 04, 05, 06	-29 -24 -31 -16	---	mA	
High-level input current	I_{IH1}	$V_{EE} = -5.2\text{ V}, V_{CC} = 0\text{ V}$ $V_{IH1} = -0.720\text{ V } @ 25^{\circ}\text{C}, -0.580\text{ V } @ 125^{\circ}\text{C}$ $-0.830\text{ V } @ -55^{\circ}\text{C}$			A11		450 1/	μA	
High-level input current	I_{IH2}	$V_{EE} = -5.2\text{ V}, V_{CC} = 0\text{ V}$ $V_{IH2} = -0.720\text{ V } @ 25^{\circ}\text{C}, -0.530\text{ V } @ 125^{\circ}\text{C}$ $-0.830\text{ V } @ -55^{\circ}\text{C}$			01 05		935 2/ 375	μA	
Low-level input current	I_{IL}	$V_{EE} = -5.2\text{ V}, V_{CC} = 0\text{ V}$ $V_{IL1} = -1.850\text{ V } @ 25^{\circ}\text{C}, -1.820\text{ V } @ 125^{\circ}\text{C}$ $-1.920\text{ V } @ -55^{\circ}\text{C}$			A11	0.3		μA	

See footnotes at end of table.

TABLE I. Electrical performance characteristics - Continued.
 (Limits are valid provided circuit is in a test socket and transverse air flow of 500 linear ft/min is maintained.)

Test	Symbol	Conditions $-55^{\circ}\text{C} \leq T_C \leq 125^{\circ}\text{C}$	Device type	Limits	Units	
				Min	Max	
Transition time, Low-to-high- level	t _{TLH}	V _{EEL} = -3.2 V, V _{CC} = +2.0 V RL = 50Ω, CL ≤ 5 pF (output under test) Load = 100Ω to GND (outputs not under test) Device type 05 only: V _{IH2} = +1.11 V V _{IL2} = +0.31 V	01,02 03,04, 06 05	1.0	4.0	ns
Transition time, high-to-low- level	t _{THL}	V _{EEL} = -3.2 V, V _{CC} = +2.0 V RL = 50Ω, CL ≤ 5 pF (output under test) Load = 100Ω to GND (outputs not under test) Device type 05 only: V _{IH2} = +1.11 V V _{IL2} = +0.31 V	01,02 03,04, 06 05	1.0	4.0	ns
Propagation delay time, low-to-high- level	t _{PLH}	V _{EEL} = -3.2 V, V _{CC} = +2.0 V RL = 50Ω, CL ≤ 5 pF (output under test) Load = 100Ω to GND (outputs not under test) Device type 05 only: V _{IH2} = +1.11 V V _{IL2} = +0.31 V	01,02 03,04, 06 05	1.0	3.7	ns
Propagation delay time, high-to-low- level	t _{PHL}	V _{EEL} = -3.2 V, V _{CC} = +2.0 V RL = 50Ω, CL ≤ 5 pF (output under test) Load = 100Ω to GND (outputs not under test) Device type 05 only: V _{IH2} = +1.11 V V _{IL2} = +0.31 V	01,02 03,04, 06 05	1.0	3.7	ns

1/ Not applicable to "B" inputs of device types 01 and 05.

2/ Applicable to "B" inputs only.

3.5 Electrical test requirements. The electrical test requirements for each device class shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table III.

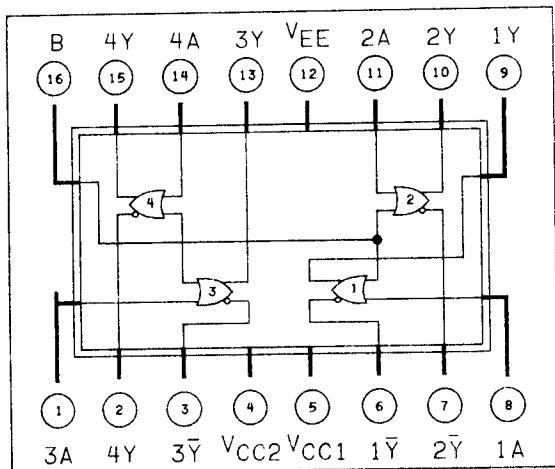
TABLE II. Electrical test requirements.

MIL-STD-883 test requirements	Subgroup (see table III)	
	Class A devices	Class B devices
Interim electrical parameters (pre burn-in) (method 5004)	1	1
Final electrical test parameters (method 5004)	1*,2,3,9	1*,2,3,9
Group A test requirements (method 5005)	1,2,3,9, 10,11	1,2,3,9
Groups C and D end-point electrical parameters (method 5005)	1,2,3	1,2,3
Additional electrical subgroups for group C periodic inspections	None	10,11

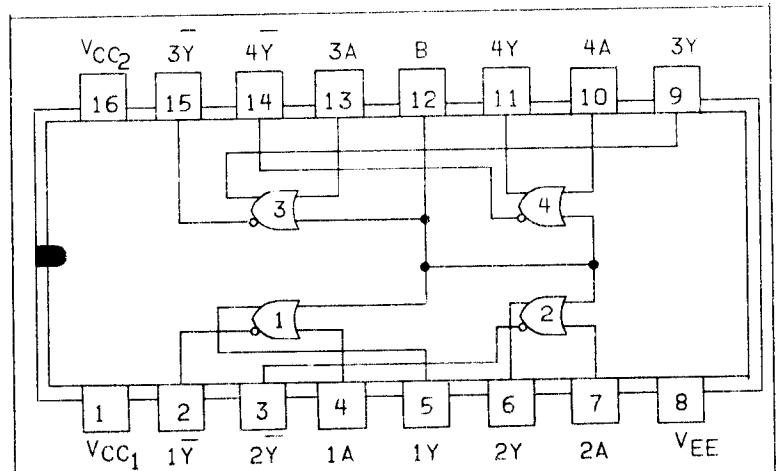
* PDA applies to subgroup 1 (see 4.2c).

Device type 01

Case F

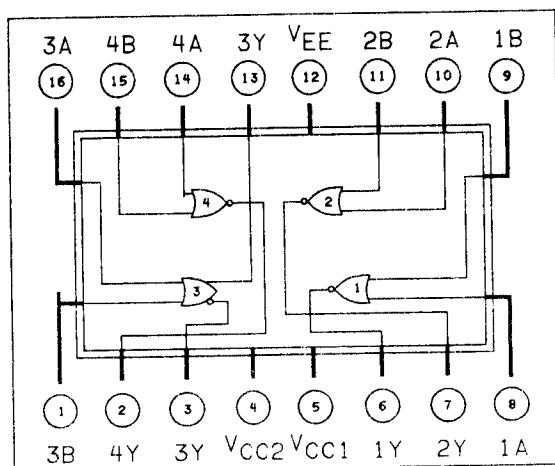


Case E



Device type 02

Case F



Case E

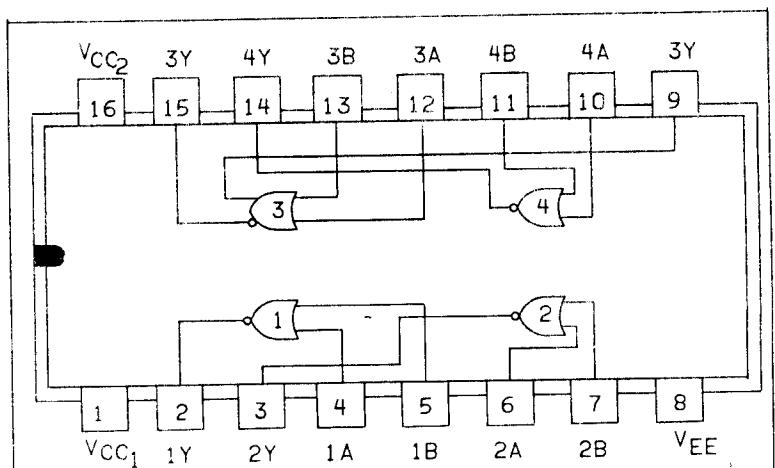


FIGURE 1. Logic diagram and terminal connections (top view).

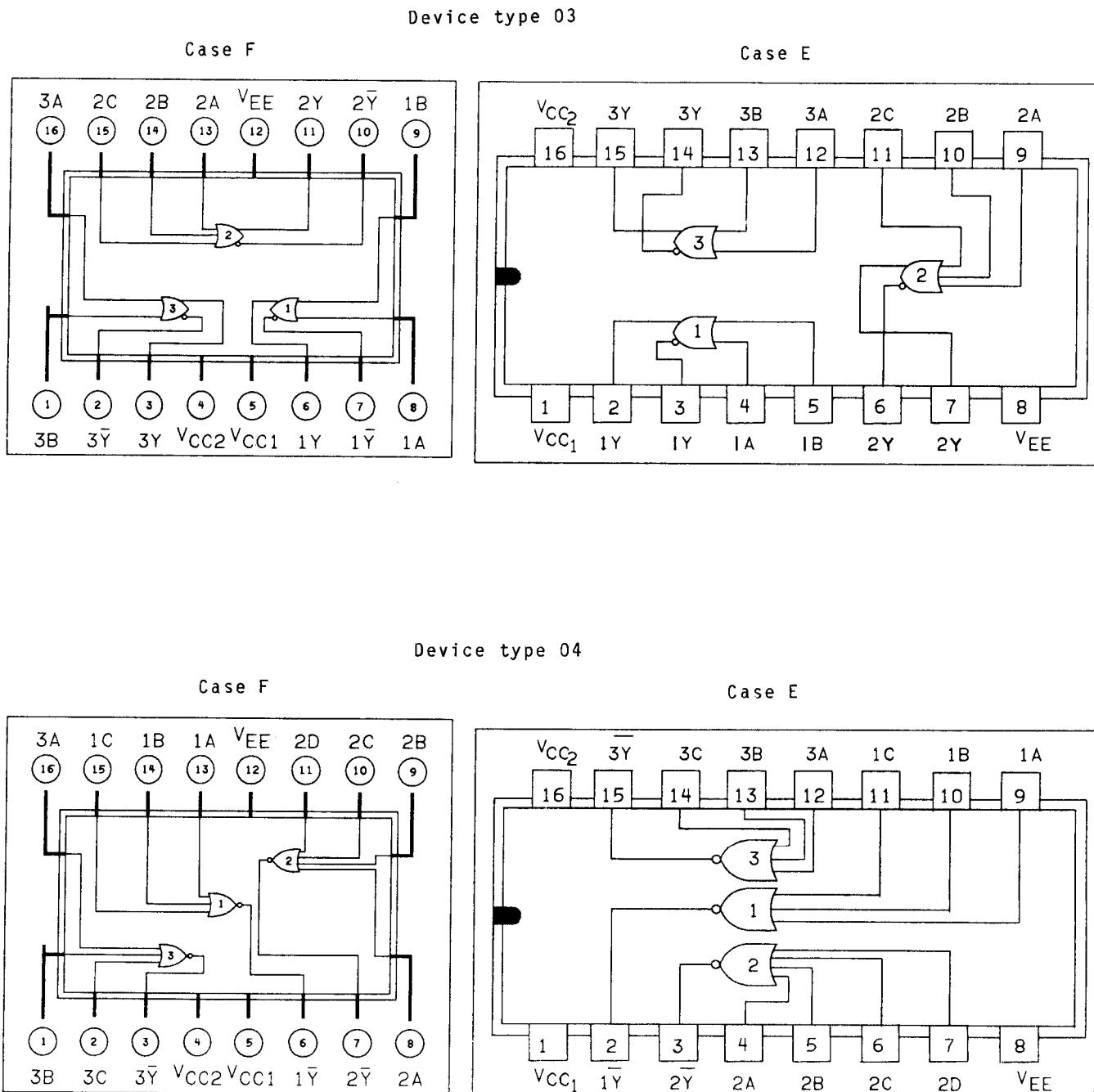
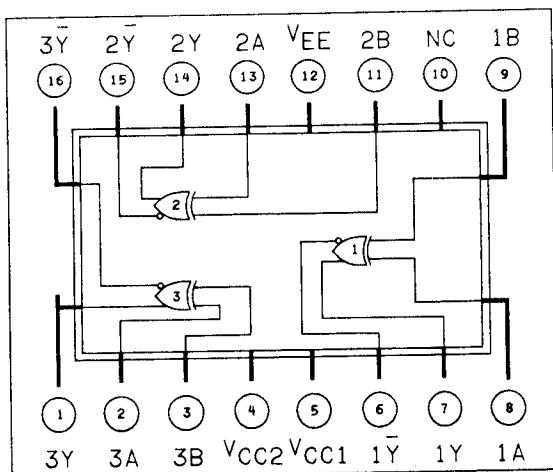


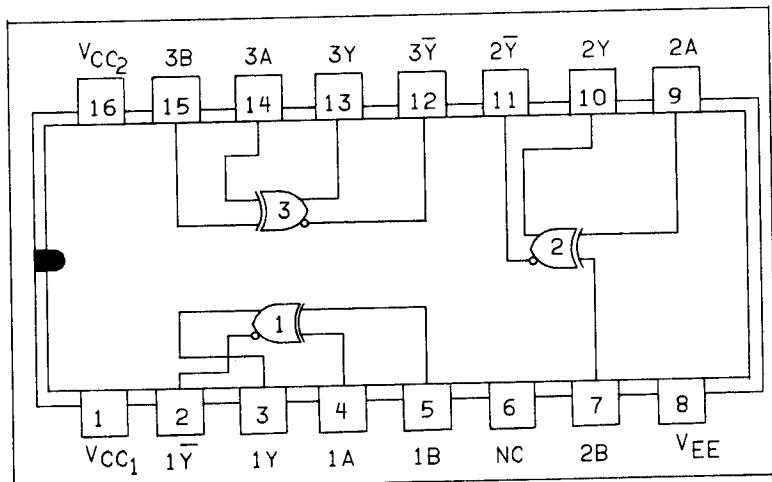
FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

Device type 05

Case F

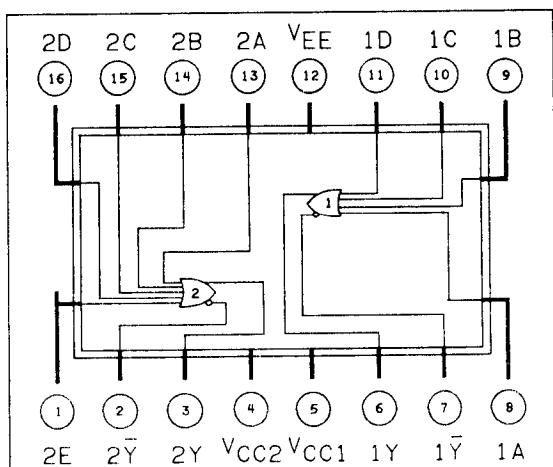


Case E

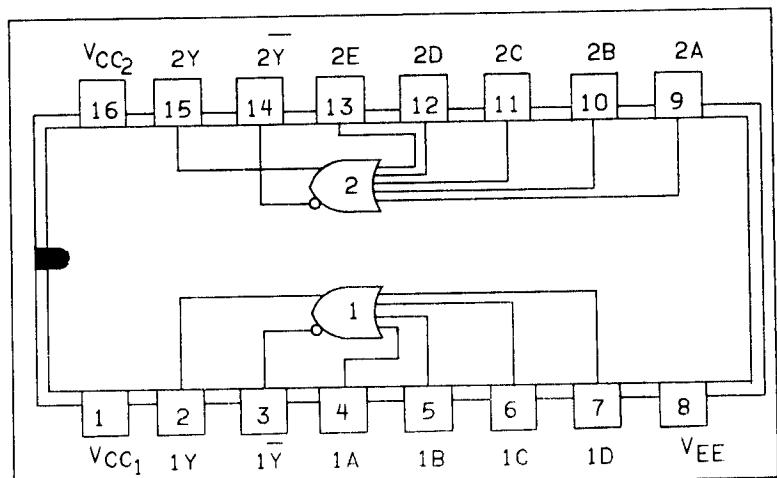


Device type 06

Case F



Case E

FIGURE 1. Logic diagram and terminal connections (top view) - Continued.

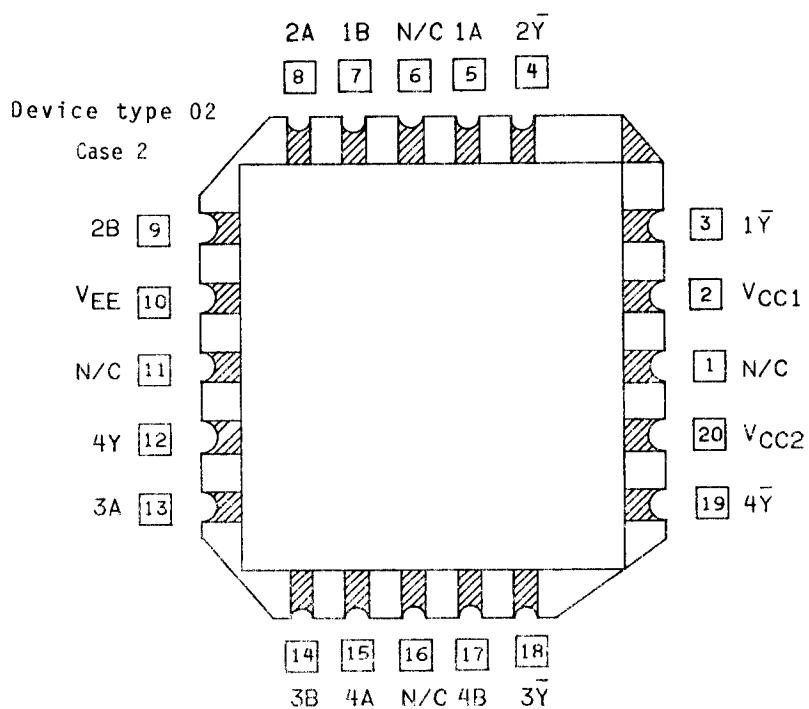
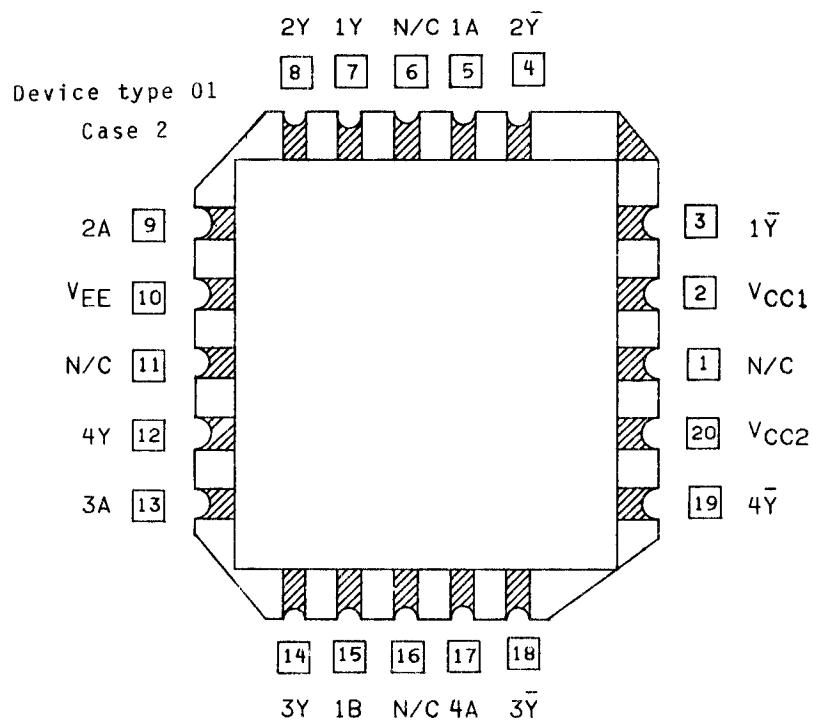
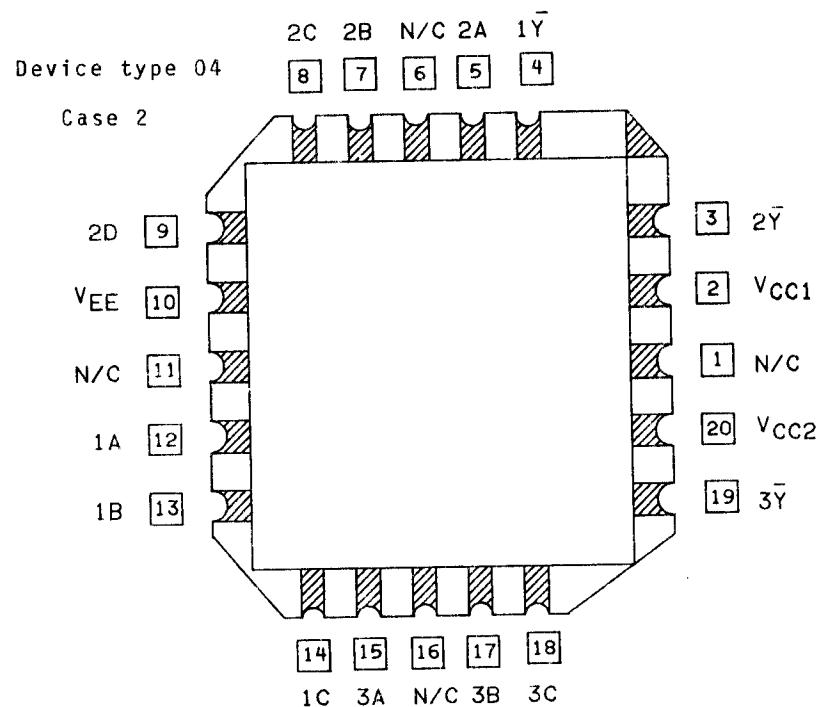
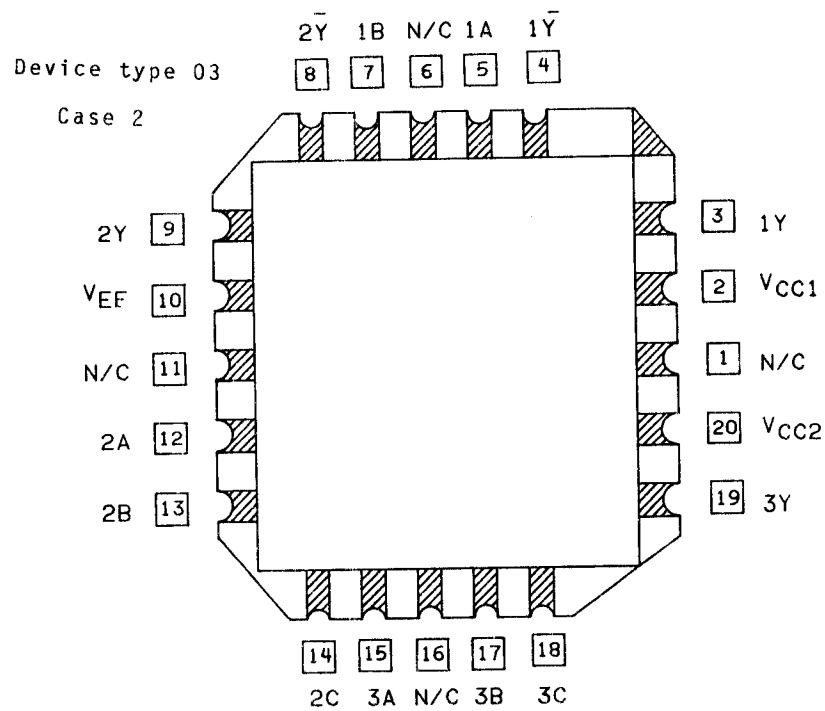
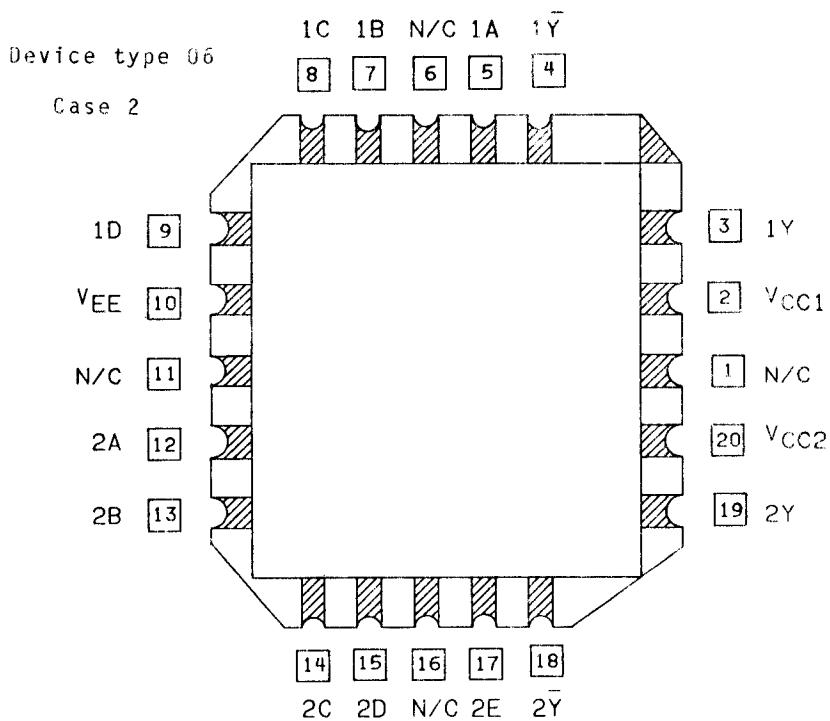
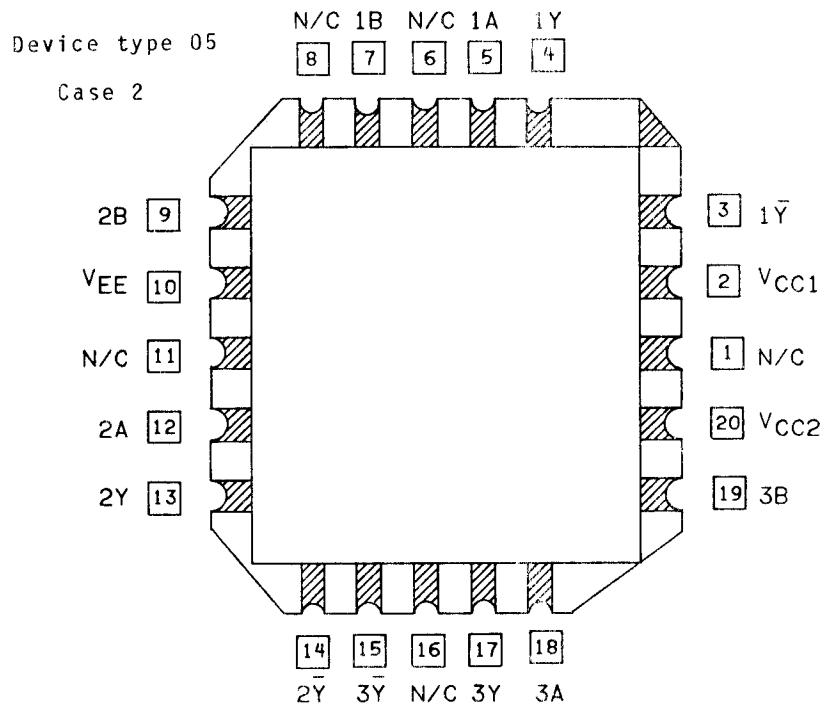


FIGURE 1. Terminal connections (top view) - Continued.

FIGURE 1. Terminal connections (top view) - Continued.

FIGURE 1. Terminal connections (top view) - Continued.

Device type 01
Truth Table
(EACH GATE)

INPUTS		OUTPUTS	
A	B	Y	\bar{Y}
L	L	L	H
H	X	H	L
X	H	H	L

H = high level

L = low level

X = irrelevant

positive logic:

$$Y = A + B$$

$$\bar{Y} = \overline{A + B}$$

Device type 02
Truth Table
(EACH GATE)

INPUTS		OUTPUTS	
A	B	Y^\dagger	Y
L	L	L	H
H	X	H	L
X	H	H	L

H = high level

L = low level

X = irrelevant

 Y^\dagger output is applicable for Gate 4 only.

positive logic:

$$Y = A + B^\dagger$$

$$\bar{Y} = \overline{A + B^\dagger}$$

Device type 03
Truth Table
(EACH GATE)

INPUTS			OUTPUTS	
A	B	C †	Y	\bar{Y}
L	L	L	L	H
H	X	X	H	L
X	H	X	H	L
X	X	H	H	L

H = high level

L = low level

X = irrelevant

 C^\dagger input and last line are applicable for Gate 2 only.

positive logic:

$$Y = A + B + C^\dagger$$

$$\bar{Y} = \overline{A + B + C^\dagger}$$

Device type 04
Truth Table
(EACH GATE)

INPUTS				OUTPUTS	
A	B	C	D †	Y	\bar{Y}
L	L	L	L	H	
H	X	X	X		L
X	H	X	X	L	
X	X	H	X		L
X	X	X	H	L	

H = high level

L = low level

X = irrelevant

 D^\dagger input and last line are applicable for Gate 2 only.

positive logic:

$$Y = A + B + C + D^\dagger$$

Device type 05
Truth Table
(EACH GATE)

INPUTS		OUTPUTS	
A	B	Y	\bar{Y}
L	L	L	H
H	L	H	L
L	H	H	L
H	H	L	H

H = high level

L = low level

positive logic:

$$Y = AB + \overline{AB}$$

$$\bar{Y} = AB + \overline{AB}$$

Device type 06
Truth Table
(EACH GATE)

INPUTS					OUTPUTS	
A	B	C	D	E †	Y	\bar{Y}
L	L	L	L	L	L	H
H	X	X	X	X	H	L
X	H	X	X	X	L	
X	X	H	X	X		L
X	X	X	H	X	H	L
X	X	X	X	H	H	L

H = high level

L = low level

X = irrelevant

 E^\dagger input and last line are applicable for Gate 2 only.

positive logic:

$$Y = A + B + C + D + E^\dagger$$

$$\bar{Y} = \overline{A + B + C + D + E^\dagger}$$

FIGURE 2. Truth tables and logic equations.

3.6 Marking. The marking shall be in accordance with MIL-M-38510.

3.7 Microcircuit group assignment. The devices covered by this specification shall be in microcircuit group number 29 (see MIL-M-38510, appendix E).

4. QUALITY ASSURANCE PROVISIONS

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-M-38510 and method 5005 and 5007 of MIL-STD-883, as applicable, except as modified herein.

4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to qualification and quality conformance inspection. The following additional criteria shall apply:

a. Burn-in test (method 1015 of MIL-STD-883).

(1) Test condition D or E using the circuit shown on figure 3, or equivalent.

(2) $T_C = 125^\circ\text{C}$ minimum.

b. Interim and final electrical test parameters shall be as specified in table II, except interim electrical parameters test prior to burn-in is optional at the discretion of the manufacturer.

c. The percent defective allowable (PDA) for class S devices shall be as specified in MIL-M-38510.

4.3 Qualification inspection. Qualification inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4 Quality conformance inspection. Quality conformance inspection shall be in accordance with MIL-M-38510. Inspections to be performed shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, and D inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection. Group A inspection shall be in accordance with table I of method 5005 of MIL-STD-883 and as follows:

a. Tests shall be as specified in table II herein.

b. Subgroups 4, 5, 6, 7 and 8 of table I of method 5005 of MIL-STD-883 shall be omitted.

4.4.2 Group B inspection. Group B inspection shall be in accordance with table II of method 5005 of MIL-STD-883. Electrical parameters shall be as specified in table II herein.

4.4.3 Group C inspection. Group C inspection shall be in accordance with table III of method 5005 of MIL-STD-883 and as follows:

a. End-point electrical parameters shall be as specified in table II herein.

b. Steady-state life test (method 1005 of MIL-STD-883) conditions, or equivalent:

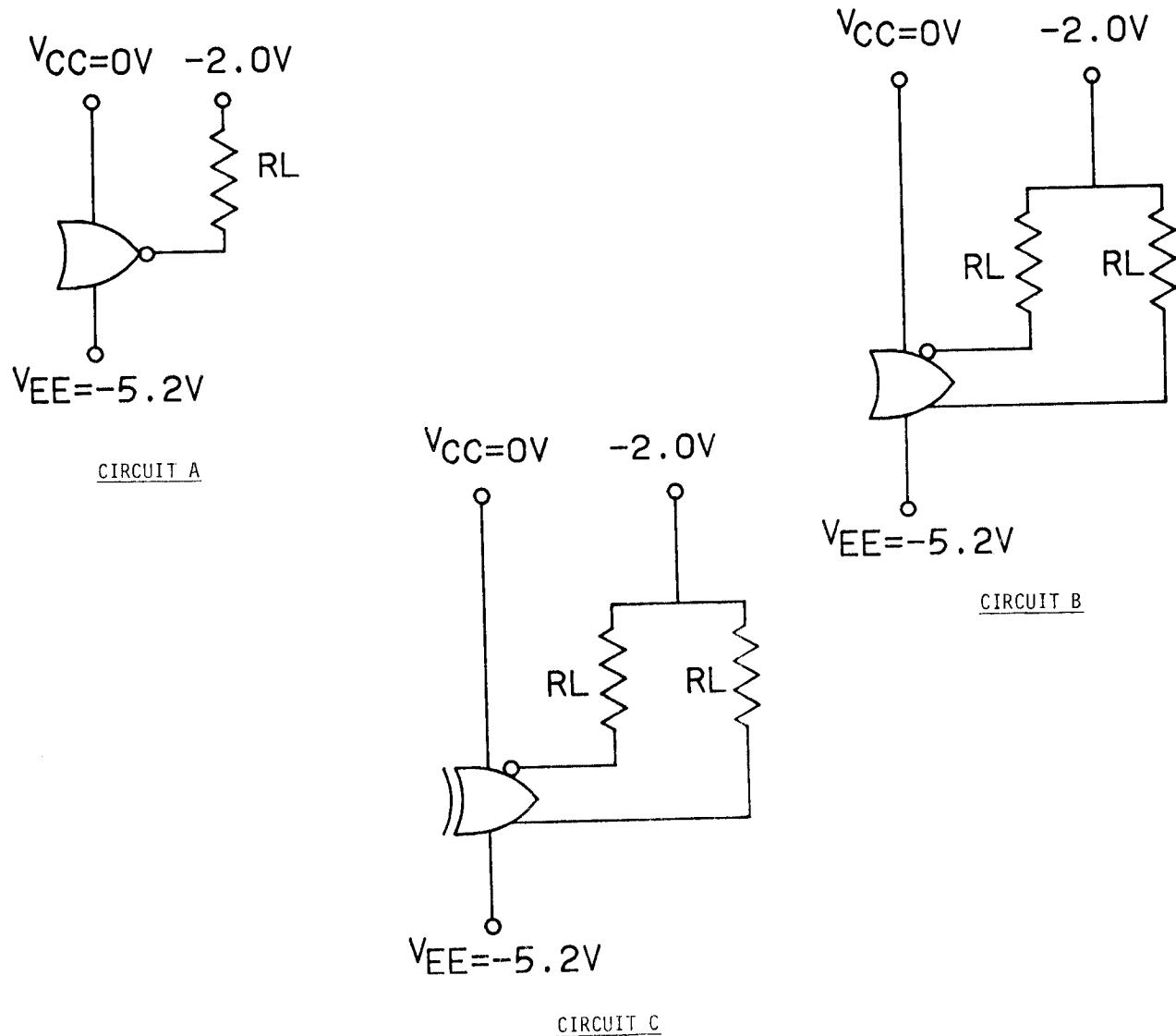
1. Test condition D or E using the circuit shown on figure 3, or equivalent.

2. $T_C = 125^\circ\text{C}$ minimum.

3. Test duration: 1,000 hours, except as permitted by appendix B of MIL-M-38510 and method 1005 of MIL-STD-883.

c. Subgroups 3 and 4 shall be added to the group C inspection requirements for class B devices and shall consist of the tests, conditions, and limits specified for subgroups 10 and 11 of group A.

4.4.4 Group D inspection. Group D inspection shall be in accordance with table IV of method 5005 of MIL-STD-883. End-point electrical parameters shall be as specified in table II herein.



NOTES:

1. Inputs are internally returned to V_{EE} through 50K ohm resistors.
2. $R_1 = 100$ ohm ($\pm 5\%$) deposited carbon rated at 70 mW at $125^\circ C$ (or equivalent).
3. Circuit A shall be used for device type 04 and gates 1, 2 and 3 of device type 02. Circuit B shall be used for device types 01, 03 and 06 and gate 4 of device type 02. Circuit C shall be used for device type 05.

FIGURE 3. Burn-in and life test circuits.

4.5 Method of inspection. Methods of inspection shall be specified as follows:

4.5.1 Voltage and current. All voltages given are referenced to the microcircuit ground terminal. Currents given are conventional and positive when flowing into the referenced terminal.

TABLE IIIA. Test conditions for all devices, group A inspection.

Symbol	V_{IH1} (V)	V_{IL1} (V)	V_{IH2} (V)	V_{IL2} (V)	V_{ITL} (V)	V_{ITH} (V)	E_1 (V)	E_2 (V)	E_3 (V)	LD_1	LD_2	in out
$T_C = 25^\circ C$	-0.780	-1.850	+1.11	+0.31	-1.475	-1.105	-5.2	-3.2	+2.0	100Ω to -2 V	100Ω to GND	See Fig 4
$T_C = 125^\circ C$	-0.630	-1.820	+1.11	+0.31	-1.400	-1.000	-5.2	-3.2	+2.0	100Ω to -2 V	100Ω to GND	See Fig 4
$T_C = -55^\circ C$	-0.880	-1.920	+1.11	+0.31	-1.510	-1.255	-5.2	-3.2	+2.0	100Ω to -2 V	100Ω to GND	See Fig 4

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

6.1 Intended use. Microcircuits conforming to this specification are intended for original equipment design applications and logistic support of existing equipment.

6.2 Ordering data. The acquisition document should specify the following:

- a. Complete part number (see 1.2).
- b. Requirements for delivery of one copy of the quality conformance inspection data pertinent to the device inspection lot to be supplied with each shipment by the device manufacturer, if applicable.
- c. Requirements for certificate of compliance, if applicable.
- d. Requirements for notification of change of product or process to the contracting activity in addition to notification to the qualifying activity, if applicable.
- e. Requirements for failure analysis (including required test condition of method 5003 of MIL-STD-883), corrective action and reporting of results, if applicable.
- f. Requirements for product assurance options.
- g. Requirements for special carriers, lead lengths, or lead forming, if applicable. These requirements shall not affect the part number. Unless otherwise specified, these requirements shall not apply to direct purchase by or direct shipment to the Government.
- h. Requirements for "JAN" marking.

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TABLE III. Group A inspection for device type 01 - Continued.

Symbol	MIL-STD-883 method	Case E Case F Case 2	Terminal test conditions	Test limits												
				Subgroup 1				Subgroup 2				Subgroup 3				
				TC = 25°C		TC = 125°C		TC = 20°C		TC = -55°C		TC = 25°C		TC = 125°C		
Symbol	Symbol	V _{CC1}	1Y 2Y 1A 1Y 2Y 2A V _{EE} 4Y 3A 3Y B 4A 3Y 4Y V _{CC2}	GND	V _{EE}	GND	V _{EE}	GND	V _{EE}	GND	V _{EE}	GND	V _{EE}	GND	V _{EE}	
Test No.	Test No.	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	E ₁	
t _{IEE}	3005	65	GND												-26	-29
t _{IHL}	3010	70	*												550	935
t _{ILH}	3009	71	*	V _{IHL}											B	550
t _{ILH}	3011	72	*	V _{IHL}												0.5
t _{ILH}	3012	73	*	V _{IHL}												0.5
t _{ILH}	3013	74	*	V _{IHL}												0.5
t _{ILH}	3014	75	*	V _{IHL}												0.5
t _{ELH}	3004	76	E ₃	L _{D2} _n 0UT	L _{D2} _n 0UT	IN	OUT	L _{D2} _n 0UT	E ₂	L _{D2} _n 0UT	IN	OUT	L _{D2} _n 0UT	E ₃	1Y 2Y 3Y 4Y	
t _{ELH}	3015	77	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3016	78	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3017	79	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3018	80	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3019	81	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3020	82	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3021	83	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3022	84	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3023	85	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3024	86	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3025	87	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3026	88	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3027	89	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3028	90	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3029	91	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3030	92	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3031	93	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3032	94	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3033	95	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3034	96	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3035	97	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3036	98	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3037	99	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3038	100	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3039	101	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3040	102	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3041	103	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3042	104	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3043	105	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3044	106	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	
t _{ELH}	3045	107	*	L _{D2} _n 0UT	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	L _{D2} _n 0UT	*	*	L _{D2} _n 0UT	*	1Y 2Y 3Y 4Y	

TABLE III. Group A inspection for device type 02.

Symbol	MIL-STD-833 method	Case E	Case F	Test 1 limits													
				1	2	3	4	5	6	7	8	9	10	11	12	13	14
V _{OH}	3006	1	GND	I _{D1L}	I _{D1H}	V _{TLL}	E _{1L}	I _{D1L}	I _{D1H}	GND	V _T	-0.930	-0.780	-0.825	-0.630	-1.080	-0.880
		2															
		3															
		4															
		5															
		6															
		7															
		8															
		9															
		10															
V _{OL}	3007	11															
		12															
		13															
		14															
		15															
		16															
		17															
		18															
		19															
		20															
V _{OTH}		21															
		22															
		23															
		24															
		25															
		26															
		27															
		28															
		29															
		30															
V _{OTL}		31															
		32															
		33															
		34															
		35															
		36															
		37															
		38															
		39															
		40															
I _{EE}		41															
I _{TH1}		42															
		43															
		44															
		45															
		46															
		47															
		48															
		49															
I _{TL}		50															
		51															
		52															
		53															

TABLE III. Group A inspection for device type 02 - Continued.

Symbol	MIL-STD-883 Method	Case E	Case F	Case G	Case outline letter, terminal number and function and test sequence. Terminal test conditions are listed in table IIIA. Terminals not designated are open.										Test limits				Subgroup 1	Subgroup 2	Subgroup 3	Unit			
					1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16					
T _{1L}		V _{CC1}	1Y	2Y	1A	1B	2A	2B	V _{EE}	4Y	3A	3B	4A	4B	3V	4V	V _{CC2}	GND	3A	0.5	0.5	JA			
																			3B	0.3	0.5	JB			
																			4A	0.3	0.5	JB			
																			4B	0.3	0.5	JB			
t _{PLH}	3004	58	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	E ₂	1V	1.1	3.3	1.0	4.0	ns
		60	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	2V	1.1	3.3	1.0	4.0	ns
		61	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	3V	1.1	3.3	1.0	4.0	ns
		62	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	4V	1.1	3.3	1.0	4.0	ns
t _{PHL}	3004	63	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	1V	1.1	3.3	1.0	4.0	ns
		64	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	2V	1.1	3.3	1.0	4.0	ns
		65	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	3V	1.1	3.3	1.0	4.0	ns
		66	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	4V	1.1	3.3	1.0	4.0	ns
t _{PLH}	3003	68	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	1V	1.0	2.9	1.0	3.7	ns
		69	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	2V	1.0	2.9	1.0	3.7	ns
		70	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	3V	1.0	2.9	1.0	3.7	ns
		71	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	4V	1.0	2.9	1.0	3.7	ns
		72	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	1V	1.0	2.9	1.0	3.7	ns
t _{PHL}	3003	73	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	2V	1.0	2.9	1.0	3.7	ns
		74	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	3V	1.0	2.9	1.0	3.7	ns
		75	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	4V	1.0	2.9	1.0	3.7	ns
		76	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	1V	1.0	2.9	1.0	3.7	ns
		77	E ₂	OUT	LD ₂ _a LD ₂ _b	IN	E ₂	LD ₂ _a	IN	IN	IN	IN	IN	IN	IN	IN	LD ₂ _a	LD ₂ _a	OUT	2V	1.0	2.9	1.0	3.7	ns

TABLE IIV. Group A inspection fr.

Symbol	Test No.	Case outline letter, terminal number, and test sequence.	Type 03.												Measured terminal				Test limits		
			Terminal test conditions are listed in Table IVA. Terminals not designated are open.				Measured terminal				Measured terminal				Subgroup 1	Subgroup 2	Subgroup 3	Unit			
MIL-STD-883 method	Case E	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	T _c = 25°C	T _c = 125°C	T _c = -55°C	Unit
Case F	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	W/n	W/n	W/n	Max	
Case Z	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	W/n	W/n	W/n	Max	
V _{OH}	3006	1	GND	I _{D1}	I _{D1}	E ₁	I _{D1}	I _{D1}	I _{D1}	I _{D1}	I _{D1}	I _{D1}	I _{D1}	I _{D1}	I _{D1}	I _{D1}	GND	I _{D1}	I _{D1}	I _{D1}	
		2																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		3																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		4																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		5																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		6																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		7																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		8																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		9																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		10																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		11																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		12																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		13																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		14																I _{D1}	I _{D1}	I _{D1}	I _{D1}
V _{OL}	3007	15																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		16																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		17																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		18																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		19																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		20																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		21																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		22																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		23																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		24																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		25																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		26																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		27																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		28																I _{D1}	I _{D1}	I _{D1}	I _{D1}
V _{OTH}	29																	I _{D1}	I _{D1}	I _{D1}	I _{D1}
		30																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		31																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		32																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		33																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		34																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		35																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		36																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		37																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		38																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		39																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		40																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		41																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		42																I _{D1}	I _{D1}	I _{D1}	I _{D1}
V _{OTh}	43																	I _{D1}	I _{D1}	I _{D1}	I _{D1}
		44																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		45																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		46																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		47																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		48																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		49																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		50																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		51																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		52																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		53																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		54																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		55																I _{D1}	I _{D1}	I _{D1}	I _{D1}
		56																I _{D1}	I _{D1}	I _{D1}	I _{D1}
I _{EE}	3005	57	"															GND	V _{EE}	-21	-24

TABLE III. Group A inspection for device type 03 - Continued.

Symbol	MIL-STD-883 method	Case E	Case F	Case G	Case H	Case I	Case J	Case K	Case L	Case M	Case N	Case O	Case P	Case Q	Case R	Case S	Case T	Case U	Case V	Case W	Case X	Case Y	Case Z	Test limits											
t _{LH}	3010	58	GND																																
		59																																	
		60																																	
		61																																	
		62																																	
		63																																	
		64																																	
t _{LL}	3009	65																																	
		66																																	
		67																																	
		68																																	
		69																																	
		70																																	
		71																																	
Subgroup 9																																			
t _{LH}	3004	72	E ₃	OUT	LD ₂ _*	IN	LD ₂ _*	IN	LD ₂ _*	OUT	LD ₂ _*	E ₂	IN	IN	IN	IN	IN	IN	LD ₂ _*	E ₃	1Y	1.1	3.3	1.0	4.0	1.0	4.0	ns							
		73																																	
		74																																	
		75																																	
		76																																	
		77																																	
t _{THL}		78																																	
		79																																	
		80																																	
		81																																	
		82																																	
		83																																	
t _{PLH}	3003	84																																	
		85																																	
		86																																	
		87																																	
		88																																	
		89																																	
t _{PHL}		90																																	
		91																																	
		92																																	
		93																																	
		94																																	
		95																																	

TABLE III. Group A inspection for device type 04.

TABLE III. Group A inspection for device type 04 - Continued.

Symbol	MIL-STD-883 method	Case outline letter, terminal number ^a and function and test sequence. Terminal test conditions are listed in table IIIA. Terminals not designated are open.												Test limits					
		Case E				Case F				Case G				Subgroup 1		Subgroup 2		Subgroup 3	
		T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	T _C	
I _{IL}	3009	52	GND											GND	3A	0.5	0.3	0.5	μA
		53												"	38	"	"	"	"
		54												"	3C	"	"	"	"
		55												"	14	"	"	"	"
		56												"	1B	"	"	"	"
		57												"	1C	"	"	"	"
		58												"	2A	"	"	"	"
		59												"	2B	"	"	"	"
		60												"	2C	"	"	"	"
		61												"	2D	"	"	"	"
Symbol 1 VCC1 Test No. 1Y 2Y 2A 2B 2C 2D 2E 1A 1B 1C 1D 1E 1F 1G 1H 1I 1J 1K 1L 1M																			
I _{TLH}	3004	62	E ₁	LD ₂ _{OUT}	LD ₂	IN	E ₂	IN	IN	IN	IN	IN	IN	LD ₂ ₁	E ₃	2Y	1.1	3.3	1.0
		63	"	"	"	"	"	"	"	"	"	"	"	"	OUT	"	1Y	"	4.0
		64	"	"	"	"	"	"	"	"	"	"	"	"	"	"	3Y	"	"
		65	"	"	OUT	LD ₂	"	"	"	"	"	"	"	"	OUT	"	"	"	"
		66	"	"	OUT	LD ₂	"	"	"	"	"	"	"	"	OUT	"	"	"	"
		67	"	"	OUT	LD ₂	"	"	"	"	"	"	"	"	OUT	"	"	"	"
I _{PLH}	3003	68	"	OUT	LD ₂ ₁	LD ₂	"	IN	"	"	"	"	"	LD ₂ ₁	"	2Y	1.1	3.3	1.0
		69	"	OUT	LD ₂ ₁	LD ₂	"	IN	"	"	"	"	"	"	OUT	"	1Y	"	4.0
		70	"	OUT	LD ₂ ₁	LD ₂	"	IN	"	"	"	"	"	"	OUT	"	3Y	"	"
I _{PIL}	3004	71	"	OUT	LD ₂ ₁	LD ₂	"	IN	"	"	"	"	"	LD ₂ ₁	"	2Y	1.0	2.9	1.0
		72	"	OUT	LD ₂ ₁	LD ₂	"	IN	"	"	"	"	"	"	OUT	"	1Y	"	3.7
		73	"	OUT	LD ₂ ₁	LD ₂	"	IN	"	"	"	"	"	"	OUT	"	3Y	"	"

TABLE III. Group A inspection for device type 05.

Case outline letter, terminal number and function and test sequence. Terminal test conditions are listed in table IIIA. Terminals not designated are open.

Case outline letter, terminal number and function and test sequence.												
Terminal test conditions are listed in table IIIA. Terminals not designated are open.												
Symbol	ML- STD-883 method	Test No.	Test limits				Measured terminal				Subgroup 3	
			$T_C = 25^\circ C$	$T_C = 125^\circ C$	$T_C = 55^\circ C$	$T_C = -55^\circ C$	V_{TH}	V_{TL}	V_{IL}	V_{IH}	Min	Max
Case E		1	2	3	4	5	6	7	8	9	10	11
Case F		2	3	4	5	6	7	8	9	10	11	12
Case G		3	4	5	6	7	8	9	10	11	12	13
Case H		4	5	6	7	8	9	10	11	12	13	14
Case I		5	6	7	8	9	10	11	12	13	14	15
Case J		6	7	8	9	10	11	12	13	14	15	16
Case K		7	8	9	10	11	12	13	14	15	16	17
Case L		8	9	10	11	12	13	14	15	16	17	18
Case M		9	10	11	12	13	14	15	16	17	18	19
Case N		10	11	12	13	14	15	16	17	18	19	20
Case O		11	12	13	14	15	16	17	18	19	20	21
Case P		12	13	14	15	16	17	18	19	20	21	22
Case Q		13	14	15	16	17	18	19	20	21	22	23
Case R		14	15	16	17	18	19	20	21	22	23	24
Case S		15	16	17	18	19	20	21	22	23	24	25
Case outline letter, terminal number and function and test sequence.												
Terminal test conditions are listed in table IIIA. Terminals not designated are open.												
Symbol	ML- STD-883 method	Test No.	Test limits				Measured terminal				Subgroup 3	
			$T_C = 25^\circ C$	$T_C = 125^\circ C$	$T_C = 55^\circ C$	$T_C = -55^\circ C$	V_{TH}	V_{TL}	V_{IL}	V_{IH}	Min	Max
V _{OL}	3006	1	GND	L_{D1_u}	V_{IH1}	V_{IL1}	E_A	D_1	L_{D1_u}	V_{IH1}	5V	3V
V _{OL}	3007	16	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	D_1	L_{D1_u}	V_{IH1}	5V	3V
V _{OL}	31	32	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	32	33	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	33	34	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	34	35	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	35	36	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	36	37	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	37	38	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	38	39	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	39	40	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	40	41	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	41	42	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	42	43	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	43	44	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	44	45	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	45	46	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	46	47	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	47	48	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	48	49	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	49	50	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	50	51	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	51	52	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	52	53	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	53	54	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	54	55	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	55	56	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	56	57	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	57	58	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	58	59	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V
V _{OL}	59	60	V_{IH1}	V_{IL1}	V_{IH1}	V_{IL1}	V_{IH1}	V_{TH}	V_{IL1}	V_{IH1}	3V	3V

TABLE III. Group A inspection for device type 05 - Continued.

TABLE III. Group A inspection for device type 05 - Continued.

Symbol	MIL-SID-863 method	Case E	Base outline letter terminal number and function and test sequence. Terminal test conditions are listed in table IIIA. Terminals not designated are open.												Test limits							
			Case F			Case Z			Subgroup 1			Subgroup 2			Subgroup 3			Measured terminal				
			1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	TC = 25°C	TC = 125°C	TC = -55°C	
Symbol	MIL-SID-863 method	Symbol	VCC1	1Y	1Y	1A	1B	2B	VEE	2A	2Y	2Y	3Y	3A	3B	V _{CC2}	Min	Max	Min	Max	Min	Max
Test No.	tpHL	113	E ₃	LD ₂	OUT	IN	V _{H2}	V _{L2}	IN	LD ₂	E ₃	1Y	1Y	1Y	1Y	1.1	3.7					
		114	E ₃	LD ₂	OUT	IN	V _{H2}	V _{L2}	IN	LD ₂	E ₃	1Y	1Y	1Y	1Y	1.0	4.5					
		115
		116
		117
		118
		119
		120
		121
		122
		123
		124
		125
		126
		127
		128
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		131
		132
		133
		134
		135
		136

TABLE III. Group A inspection for device type 06.

Symbol	MIL-STD-883 Method	Test No.	Case outline letter, terminal number and function and test sequence. Terminal test conditions are listed in table IIIA. Terminals not designated are open.												Test limits								
			(Case E) Terminal 1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20	Measured terminal
V _{OH}	3006	1	GND	I _{LD1n}	I _{LD1n}	V _{IHL}	V _{IHL}	E ₁															-0.930
		2	GND																				-0.780
		3																					-0.825
		4																					-0.630
		5																					-1.080
		6																					Y
		7																					
		8																					
		9																					
		10																					
		11																					
		12																					
		13																					
		14																					
		15																					
		16																					
		17																					
		18																					
V _{OL}	3007	19																					-1.850
		20																					-1.820
		21																					-1.545
		22																					-1.920
		23																					-1.655
		24																					
		25																					
		26																					
		27																					
		28																					
		29																					
		30																					
		31																					
		32																					
		33																					
		34																					
		35																					
		36																					
V _{OTH}		37																					-0.845
		38																					-1.100
		39																					
		40																					
		41																					
		42																					
		43																					
		44																					
		45																					
		46																					
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		48																					
		49																					
		50																					
		51																					
		52																					
		53																					
		54																					

TABLE III. Group A inspection for device type 06 - Continued.

Case outline letter, terminal number and function and test sequence. Terminal test conditions are listed in table IIIA. Terminals not des-

TABLE III. Group A inspection for device type 06 - continued.

Symbol	MIL-STD-883 Method	Case outline letter, terminal number and function and test sequence. Terminal test conditions are listed in Table III. Terminals not designated are open.																Test limits						
		Case E	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	Measured terminal	Subgroup 1	Subgroup 2	Subgroup 3	Unit		
Case 1	5	6	7	8	9	10	11	12	13	14	15	16	1	2	3	4	$T_C = 25^\circ C$	$T_C = 125^\circ C$	$T_C = -55^\circ C$	$T_C = -55^\circ C$				
Case 2	3	4	5	7	8	9	10	12	13	14	15	17	18	19	20									
Symbol	Wcc1	1Y	1Y	1A	1B	1C	1D	V _{EF}	2A	2B	2C	2D	2E	2Y	V _{CC2}		Min	Max	Min	Max	Min	Max		
Test No.	100	E ₂	OUT	LD ₂ _* OUT	LD ₂ _*	LD ₂ _*										E ₃	1Y	1.0	2.9	1.0	3.7	1.0	3.7	
t _{PLH}	3003	101	E ₂	OUT	LD ₂ _* OUT	LD ₂ _*	IN	IN	E ₂	IN	IN	IN	IN	IN		LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7	
	-	102	-	-	-	-	-	-	-	-	-	-	-	-	-	OUT	LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7
	-	103	-	-	-	-	-	-	-	-	-	-	-	-	-	OUT	LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7
t _{POL}	-	104	-	-	-	-	-	-	-	-	-	-	-	-	-	LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7	
	-	105	-	-	-	-	-	-	-	-	-	-	-	-	-	OUT	LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7
	-	106	-	-	-	-	-	-	-	-	-	-	-	-	-	OUT	LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7
	-	107	-	-	-	-	-	-	-	-	-	-	-	-	-	OUT	LD ₂ _*	1Y	1.0	2.9	1.0	3.7	1.0	3.7

6.3 Abbreviations, symbols, and definitions. The abbreviations, symbols, and definitions used herein are defined in MIL-M-38510, MIL-STD-133I, and as follows:

GND - - - - -	Ground zero voltage potential
VOTH - - - - -	High-level threshold output voltage
VOTL - - - - -	Low-level threshold output voltage
VITH - - - - -	High-level threshold input voltage
VITL - - - - -	Low-level threshold input voltage
V _{EEL} - - - - -	Shifted power supply voltage for the purpose of ac testing
T _J - - - - -	Circuit junction temperature
T _C - - - - -	Case operating temperature
P _D - - - - -	Circuit power dissipation
θ _{JA} - - - - -	Junction to ambient thermal resistance in °C per watt
θ _{JC} - - - - -	Junction to case thermal resistance

6.4 Logistic support. Lead materials and finishes (see 3.3) are interchangeable. Unless otherwise specified, microcircuits acquired for Government logistic support will be acquired to device class B (see 1.2.2), lead material and finish C (see 3.3). Longer length leads and lead forming shall not affect the part number.

6.5 Substitutability. The cross-reference information below is presented for the convenience of users. Microcircuits covered by this specification will functionally replace the listed generic-industry type. Generic-industry microcircuit types may not have equivalent operational performance characteristics across military temperature ranges or reliability factors equivalent to MIL-M-38510 device types and may have slight physical variations in relation to case size. The presence of this information shall not be deemed as permitting substitution of generic-industry types for MIL-M-38510 types or as a waiver of any of the provisions of MIL-M-38510.

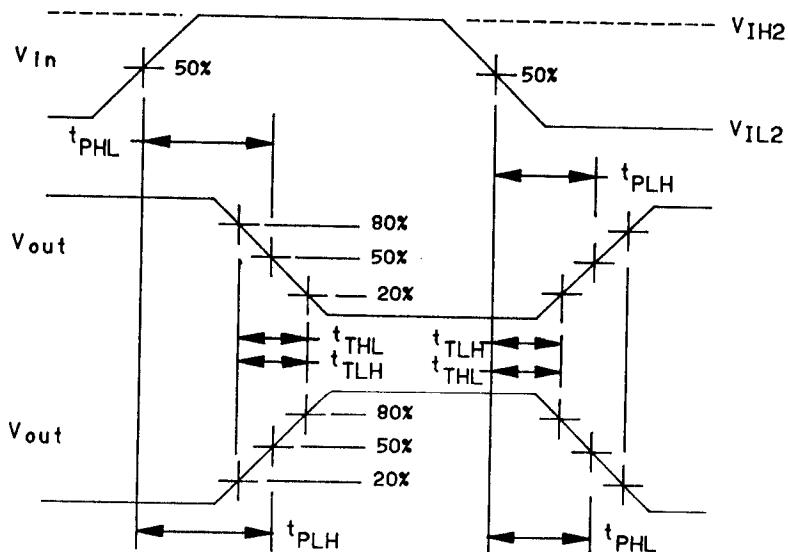
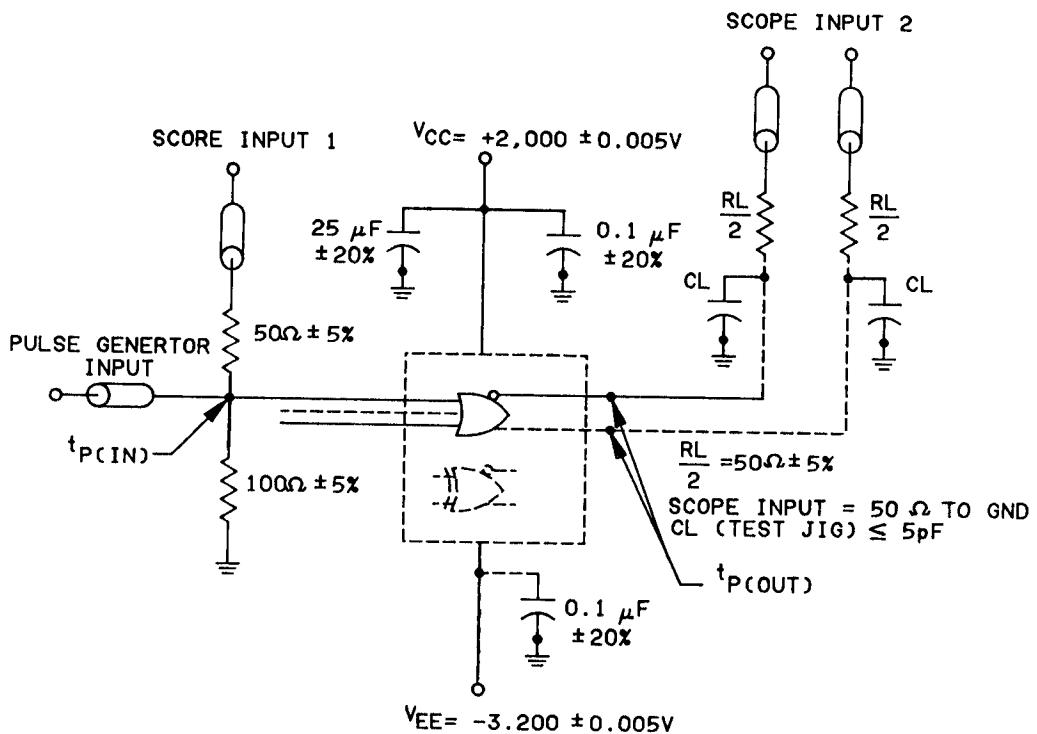
<u>Device type</u>	<u>Commerical type</u>
01	10501
02	10502
03	10505
04	10506
05	10507
06	10509

6.6 Environmental variations versus device testing and operation. Different nominal values of air velocity and temperature may be selected for device tests and in-system operation. However, when this occurs or when air velocity and temperature gradients cause a shift in device junction temperature greater than ±2°C, the device output voltages and input forcing functions assume significant new values. Based on the typical thermal resistance curve of figure 8, the new values can be determined from the procedures in 6.6.1.

6.6.1 Procedures for determining new values of device output voltage and input forcing function.

- a. Determine device power dissipation by power supply drain current and the following equation:

$$P_D \text{ (max)} = I_{EE} \text{ (max)} \times V_{EE} + 9.7 \text{ mW} \times \text{number of outputs.}$$
- b. Using this maximum power dissipation, enter figures 5 and 6 as applicable for the case outline and determine the junction temperature deviation (ΔT_J) for the selected nominal air velocity.
- c. If the actual ambient test or system temperatures are other than those specified (-55°C, 25°C, 125°C), the difference between the actual and specified values shall be algebraically added to the ΔT_J for the air velocity determined in (b) above to obtain a ΔT_J (total).
- d. Using the appropriate adjustment coefficients from figure 7 multiplied by the ΔT_J (total), determine the correct amount of compensation to be applied to each of the forcing functions and voltage limits under the actual test or system conditions. (see 6.6.2 for two examples of determining compensation.)



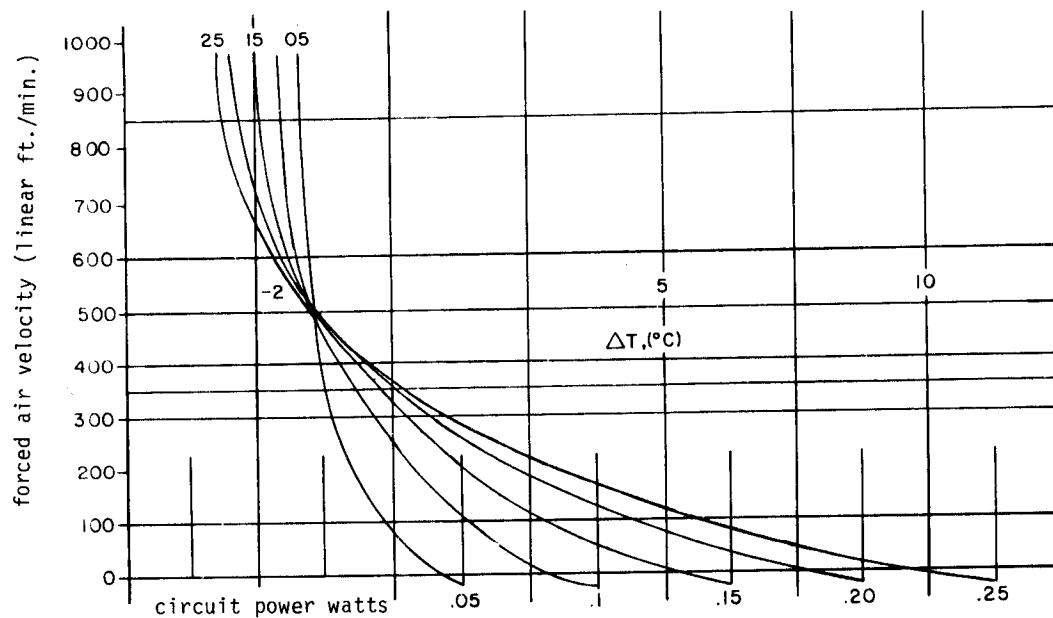
T_C	V_{IH2} $(\pm 10 \text{ mV})$	V_{IL2} $(\pm 10 \text{ mV})$
$25^\circ C$	+1.11 V	+0.31 V
$125^\circ C$	+1.24 V	+0.36 V
$-55^\circ C$	+1.01 V	+0.28 V

$t_p = 40 \text{ ns} = 1 \text{ ns}$
 $Z_{OUT} \approx 50\Omega$
 $t_{THL} = 2.0 \text{ ns } (20\% - 80\%) \pm 0.2 \text{ ns}$
 $t_{TLH} = 2.0 \text{ ns } (20\% - 80\%) \pm 0.2 \text{ ns}$
 $PRR = 1.00 \text{ MHz} \pm 0.05 \text{ MHz}$

NOTES:

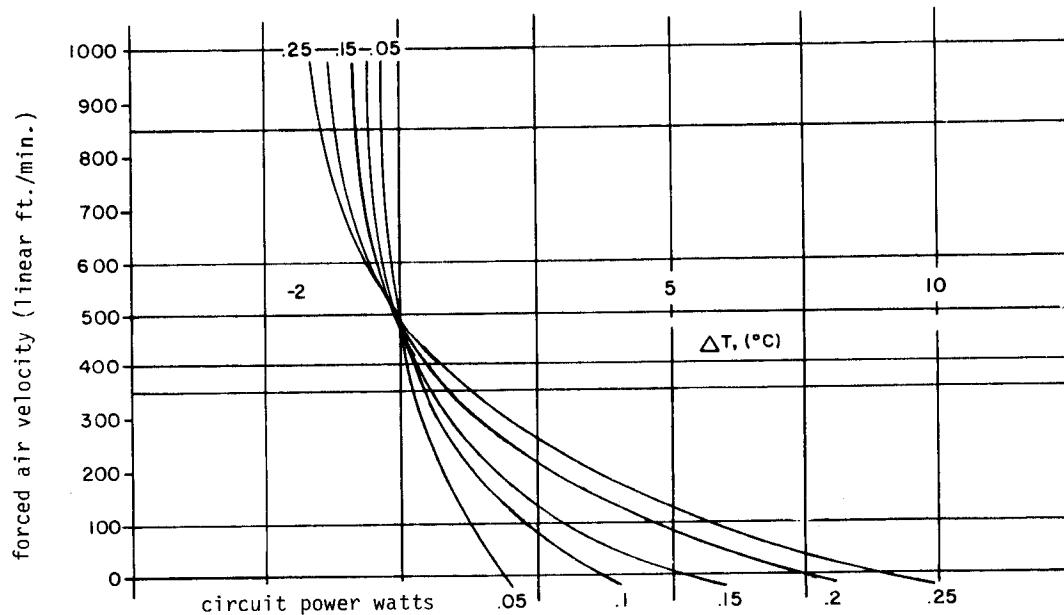
1. Perform test in accordance with test table; each output is tested separately.
2. All input and output cables to the scope are equal lengths of 50Ω coaxial cables. Wire length should be ≤ 0.250 (6.35 mm) from $t_p(IN)$ to input pin and $t_p(OUT)$ to output pin.
3. Outputs not under test connected to 100Ω resistor to ground.

FIGURE 4. Switching time test circuit and waveforms.



NOTE: Change in junction temperature versus forced air velocity, ref. to 500 linear ft./min.
circuit power as variable parameter 100 Ω load.

FIGURE 5. Junction temperature versus air velocity case E.

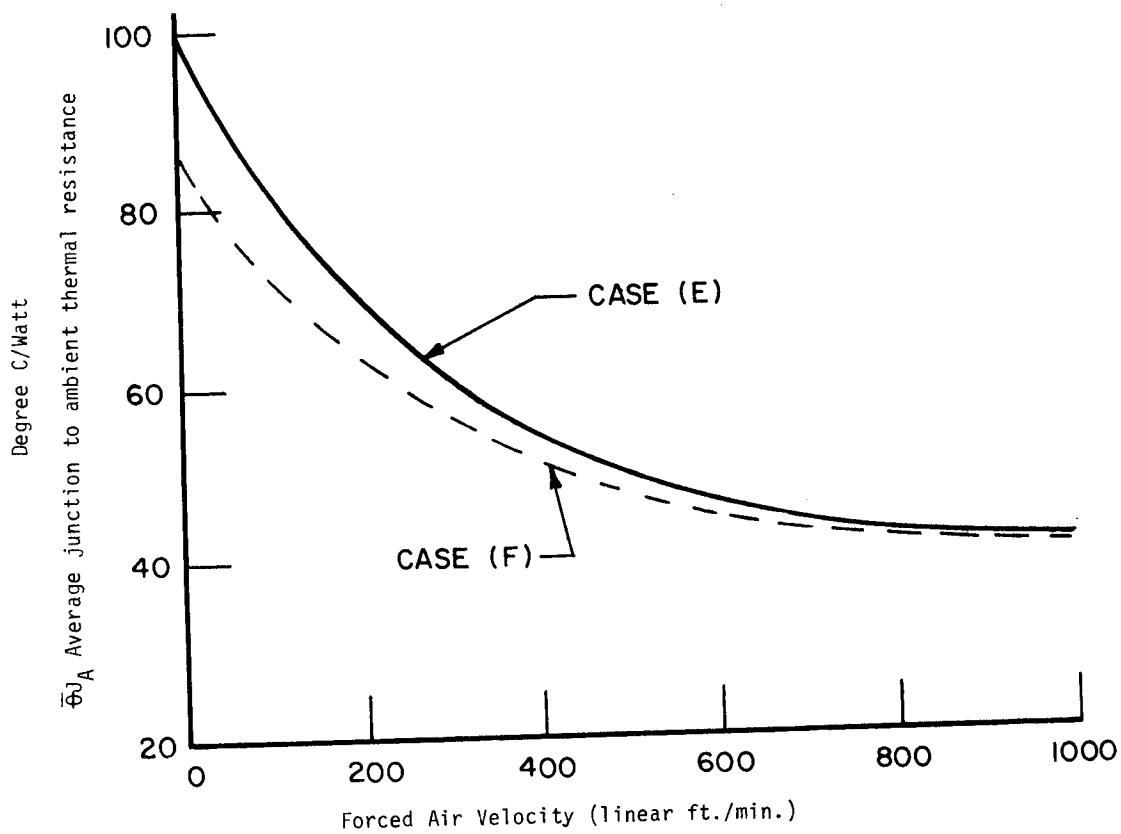


NOTE: Change in junction temperature versus forced air velocity, ref. to 500 linear ft./min.
circuit power as variable parameter 100 Ω load.

FIGURE 6. Junction temperature versus air velocity case F.

PARAMETER	-55°C (mV/°C)		+25°C (mV/°C)		+125°C (mV/°C)	
	+ΔT _J	-ΔT _J	+ΔT _J	-ΔT _J	+ΔT _J	-ΔT _J
V _{OH} max, V _{IH}	1.38	1.38	1.40	1.38	1.40	1.40
V _{OH} min, V _{OTH}	1.88	1.88	1.05	1.88	1.05	1.05
V _{OL} max, V _{OTL}	0.44	0.44	0.75	0.44	0.75	0.75
V _{OL} min, V _{IL}	0.88	0.88	0.30	0.88	0.30	0.30
V _{ITH}	1.88	1.88	1.05	1.88	1.05	1.05
V _{ITL}	0.44	0.44	0.75	0.44	0.75	0.75

FIGURE 7. Adjustment coefficients for forcing function and test limit compensation.



NOTE:
 $(\theta_{JA} - \text{vs- Forced Air Velocity})$ For case (E) and (F)
 $T_J = T_c + \theta_{JA} \times P_D$ (max).

FIGURE 8. Air velocity vs thermal resistance.

6.6.2 Test limit compensation examples.

- a. A device which has a power dissipation of 100 mW in case E is to be tested under a zero air flow condition. On figure 5 ΔT_J between 500 linear ft/min and zero air flow is +4°C. In order to adjust the various parameter limits, use figure 7 which defines the limit adjustment coefficients for ΔT_J . To adjust $V_{OH}(\max)$ at -55°C, use the $+\Delta T_J$ column of the -55°C portion of figure 7 and locate the coefficient corresponding to $V_{OH}(\max)$. This value is 1.38 mV/°C. Multiply the ΔT_J by the coefficient and algebraically add it to the -55°C $V_{OH}(\max)$ limit from table III.

$$\begin{aligned} V_{OH}(\max) \text{ (adjusted limit)} &= (+4^\circ\text{C}) \times (1.38 \text{ mV/}^\circ\text{C}) + (-830 \text{ mV}) \\ &= 5.52 \text{ mV} - 830 \text{ mV} = 824.48 \text{ mV} \\ &\text{Use } - 824 \text{ mV} \end{aligned}$$

Follow the same procedure to adjust the remaining parameters at -55 as well as all parameters at 25°C and 125°C.

- b. A device with a power dissipation of 150 mW in case E is to be tested at an air flow of 200 Linear ft/min and the 25°C testing is to be accomplished at an ambient temperature of +20°C. On figure 5 ΔT_J due to air flow is +2°C. The ΔT_J due to ambient temperature change is -5°C (25-20). Therefore the total $\Delta T_J = -5 + 2 = -3^\circ\text{C}$. Using figure 7, find the 25°C, $-\Delta T_J$ column. To adjust $V_{OL}(\max)$ locate the limit coefficient corresponding to $V_{OL}(\max)$ for a negative ΔT_J , this value is 0.44 mV/°C. Multiply the ΔT_J by the coefficient and algebraically add it to the +25°C $V_{OL}(\max)$ limit from table III.

$$\begin{aligned} V_{OL}(\max) \text{ (adjusted limit)} &= (-3^\circ\text{C}) \times (0.44 \text{ mV/}^\circ\text{C}) + (-1620 \text{ mV}) \\ &= 1.32 \text{ mV} - 1620 \text{ mV} = 1621.32 \text{ mV} \\ &\text{Use } - 1621 \text{ mV} \end{aligned}$$

Follow the same procedure to adjust the remaining parameters at 25°C.

- 6.6.3 Maximum junction temperature.** Under no circumstance should the devices be operated in an environment such that T_J as calculated by the following equation be allowed to exceed the maximum junction temperature rating of 1.2.4. $T_J = T_C + \theta_{JA} \text{ (TYP)} \times P_D \text{ (max)}$. Typical junction to ambient thermal resistance θ_{JA} (TYP) varies as a function of air velocity as shown on figure 8.

- 6.7 Changes from previous issue.** Asterisks are not used in this revision to identify changes with respect to the previous issue due to the extensiveness of the changes.

Custodians:
 Army - ER
 Navy - EC
 Air Force - 17

Preparing activity:
 Air Force - 17
 (Project 5962-0784-1)

Review activities:
 Army - AR, MI
 Navy - SH, OS, TD
 Air Force - 11, 19, 85, 99
 DLA - ES

User activities:
 Army - SM
 Navy - AS, CG, MC

Agent:
 DLA - ES